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ISO 9001:2008
ISO 13485:2003

Quick Turn IC Assembly, Pre-Asia Volume Production, Advanced Packaging Development and Assembly, ITAR Registered, ISO 13485 Medical Certified

IC ASSEMBLY - PLASTIC PACKAGES: Commercial, MIL-STD-883			
Package Type	Lead Count	Body Size	Solder
SOIC	8, 16 (heat sink option)	0.150"	Plate
	14	0.150"	Plate
	16, 20, 24, 28	0.300"	Coat
QSOP	16 (heat sink option)	0.150"	Plate
SSOP	30	5.3 mm	Plate
MSOP	8, 10	3.0 mm	Plate
TSSOP	20, 28	4.4 mm	Plate
PDIP	14, 16, 20, 24, 28	0.300"	Coat
	24, 28, 40	0.600"	Coat

QFN, TQFN, DFN: JEDEC MO-220, MO-229, stacked die, SiP & MEMS RoHS compliant, custom versions in 4 – 5 weeks, copper wire bonding available					
Size (mm)	QFN Lead Count	DFN Lead Count	Pitch (mm)	QFN Height (mm)	TQFN
2x2		6, 8, 10	0.50	0.90 nom.	0.75 nom.
2x3		10, 12	0.50	0.90	0.75
3x3	8 / 12, 16 / 20	8, 10	0.65 / 0.50 / 0.40	0.90	0.75
3x4		12	0.50	0.90	0.75
4x4	16 / 20, 24 / 28	12	0.65 / 0.50 / 0.40	0.90	0.75
5x5	20 / 28, 32 / 36, 40		0.65 / 0.50 / 0.40	0.90	0.75
6x6	40 / 48, 52		0.50 / 0.40	0.90	0.75
7x7	48 / 56, 60		0.50 / 0.40	0.90	0.75
8x8	52, 56 / 68		0.50 / 0.40	0.90	0.75
9x9	64		0.50	0.90	0.75
10x10	72		0.50	0.90	0.75
12x12	100		0.40	0.90	0.75

IC ASSEMBLY – CERAMIC PACKAGES
Multilayer 8L through 447 L packages
PGA (pin up & pin down), LCC, Flat Pack, QFP, DIP
Die attach: Eutectic, Polyimide, JM7000, Epoxy Wire Bond: Al, Au, Cu (0.8 - 2 mil standard) Seal: Solder (AuSn), Glass, Adhesive
CDIP, CQUAD, CPAC: 8L through 256L packages
Die attach: Eutectic, Polyimide Wire bond: Ultrasonic Al Seal: Glass Lead finish: Solder coat

ADVANCED PACKAGING, PACKAGE DEVELOPMENT & OTHER SERVICES
SiP: 2D system, 3D system, stacked die, flip chip, SMT – over molded / Si, SiGe, GaAs Devices
CSP, Multi-Chip (MCM), High Frequency RF Modules, Hybrid Assembly
Chip-on-Board (COB), Chip-on-Flex (COF), Flip Chip Technologies including ACF
Wafer sawing (including 300 mm) & die processing: Commercial & MIL-STD-883 Condition A (Class S) & Condition B
Wire Bonding: Au ball, Au Wedge, Al Wedge, Copper, Controlled Loop RF Wedge & Ribbon
Medical Devices / MEMS Packaging / LED Arrays & Modules / Microelectronics Assembly

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Silicon Valley's Packaging Foundry

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